

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	9293	(@ad<"20010313") and (chip or die or chips or dies) and capacitor and (encapsulant or encapsulate or package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 12:14
L8	6918	L7 and ((locate or location or anywhere or mount or place or position) and capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:24
L9	5332	L8 and (substrate or board or interposer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:19
L10	3520	L9 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:20
L12	1403	L10 and "257"/\$.ccls. and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:22
L13	192	L7 and ((locate or location or anywhere or mount or place or position) near capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 11:24
L14	21	L7 and (placement near capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 11:53
L15	1	Decoupling adj Capacitor adj Placement	IBM_TDB	OR	OFF	2005/02/03 11:28
L16	30545	(@ad<"20010313") and (chip or die or chips or dies) and capacitor and (substrate or board or interposer or spacer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 11:32

L17	9906	L16 and (capacitor with (substrate or board or interposer or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 11:33
L18	1	("6407456").PN.	USPAT	OR	OFF	2005/02/03 11:36
L19	2	("3187253").PN.	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:37
L20	0	("30187253").PN.	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:36
L21	2	("3187253").PN.	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:36
L22	3	"03187253"	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:40
L23	3	"6462412"	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:47
L24	3	"2001102512"	USPAT; JPO; DERWENT	OR	OFF	2005/02/03 11:49
L25	0	("20020195705").PN.	USPAT	OR	OFF	2005/02/03 11:50
L26	1	("20020195705").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/03 11:50
L27	1	("6356453").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/03 11:51
L28	1	("5808878").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/03 11:52
L29	1	("6441483").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/03 11:52
L30	265	L7 and (density with capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 11:53
L31	571	(@ad<"20010313") and (chip or die or chips or dies) and (capacitor with (cap or lid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 12:17

L32	5	L31 and 257/686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 12:16
S1	110	(@ad<"20010313") and 257/686. ccls. and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 14:58
S2	108	(@ad<"20010313") and 257/777. ccls. and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 15:04
S3	549478	S2 ot S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 15:04
S4	68	S2 not S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 14:58
S5	77	(@ad<"20010313") and 257/786. ccls. and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:16
S6	549482	S5 ot S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 15:04
S7	72	S5 not S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 15:05

S8	70	S7 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/02 15:05
----	----	-----------	---	----	-----	------------------